

Application No.: 10/802,544

Amendment dated: February 23, 2006

Reply to Office Action dated: November 23, 2005

AMENDMENTS TO THE CLAIMS

1-9. (Cancelled)

10. (Original) A method for manufacturing a magnetic head arm assembly (HAA)

comprising:

providing a head gimbal assembly (HGA), said HGA having an HGA mating portion;

providing a flexible printed circuit (FPC) assembly, said FPC having an FPC mating portion;

providing an actuator coil assembly, said actuator coil assembly having a first mating portion and a second mating portion, wherein each of said HGA, FPC assembly, and actuator coil assembly is manufactured independently from each other;

coupling said HGA mating portion to said actuator coil assembly first mating portion; and

coupling said FPC mating portion to said actuator coil assembly second mating portion.

11. (Original) The method of claim 10, wherein said actuator coil assembly first mating portion and second mating portion each have substantially smooth interface surfaces, and wherein said HGA mating portion and FPC mating portion each have substantially smooth interface surfaces.

12. (Original) The method of claim 11, wherein said actuator coil assembly first mating portion and second mating portion each have substantially flat interface surfaces, and wherein said HGA mating portion and FPC mating portion each have substantially flat interface surfaces.

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13. (Original) The method of claim 12, wherein said actuator coil assembly first mating portion is recessed and contoured to interface said HGA mating portion and wherein said actuator coil assembly second mating portion is contoured to interface said FPC mating portion.

14. (Original) The method of claim 12, wherein at least one of said HGA, said FPC assembly, and said actuator coil assembly is manufactured by injection molding.

15. (Original) The method of claim 14, wherein said HGA is a unimount HGA.

16. (Original) The method of claim 15, wherein said unimount HGA includes a unimount baseplate containing said HGA mating portion, a multi-piece loadbeam, a flex-suspension assembly (FSA) trace, and a slider device.

17. (Original) The method of claim 16, wherein said FPC assembly includes a plastic bracket, a metal bracket containing said FPC mating portion, and a flexible printed circuit.

18. (Original) The method of claim 17, wherein said actuator coil assembly includes a coil and an actuator body containing said first and second mating portions.

19. (Withdrawn) The method of claim 18, wherein said FPC is coupled to said actuator body by rivet deformation.

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20. (Withdrawn) The method of claim 18, wherein said FPC is coupled to said actuator body by adhesive bonding.

21. (Original) The method of claim 18, wherein said FPC is coupled to said actuator body by solder bonding.

22. (Withdrawn) The method of claim 18, wherein said coil is coupled to an FPC trace by solder bonding.

23. (Withdrawn) The method of claim 18, wherein said coil is coupled to an FPC trace by stitch bonding.

24. (Withdrawn) The method of claim 18, wherein said HGA assembly is coupled to said FPC assembly by adhesive bonding.

25. (Withdrawn) The method of claim 18, wherein said HGA assembly is coupled to said FPC assembly by rivet deformation.

26. (Withdrawn) The method of claim 18, wherein said HGA assembly is coupled to said FPC assembly by screw mounting.

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27. (Withdrawn) The method of claim 18, wherein said FSA trace is coupled to a bonding pad of said FPC assembly by tape automated bonding (TAB).
28. (Withdrawn) The method of claim 18, wherein said FSA trace is coupled to a bonding pad of said FPC assembly by anisotropic conductive film (ACF) bonding.
29. (Withdrawn) The method of claim 18, wherein said multi-piece loadbeam is coupled to said unimount baseplate by laser welding.
30. (Withdrawn) The method of claim 18, wherein said FSA trace is coupled to said HGA assembly by ultra-violet (UV) epoxy bonding.
31. (Withdrawn) The method of claim 18, wherein said FPC assembly is coupled to said metal bracket by lamination.
32. (Withdrawn) The method of claim 18, wherein said FPC assembly is coupled to said plastic bracket by pin insertion.
33. (Withdrawn) The method of claim 18, wherein said coil is coupled to said actuator body by epoxy.